

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	51	("438"/460-465.ccls. "29"/\$.ccls.) and (((board printed) near4 circuit) ((board mount\$3) near4 substrate)) and (electroplat\$5 plat\$3) near5 (line wire) and (au gold) and (cut\$4 dicing) near10 (electrode terminal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/22 13:37
L2	88	("438"/460-465.ccls. "29"/\$.ccls.) and (((board printed) near4 circuit) ((board mount\$3) near4 substrate)) and (electroplat\$5 plat\$3) near5 (line lead wire) and (au gold) and (cut\$4 dicing) near10 (electrode terminal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/22 14:48
L3	7	("5231751" "5373627" "5388328" "5821626" "6159853" "6617681" "6662442").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/22 14:18
L4	8	("3325882" "3614832" "3781596" "3821847" "3838984" "3996603").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/22 14:43
L7	9	("438"/460-465.ccls. "29"/\$.ccls.) and (((board printed) near4 circuit) ((board mount\$3) near4 substrate)) and (electroplat\$5 plat\$3) near5 (line lead wire) and (au gold) and (dicing) near10 (electrode terminal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/22 14:49
S1	24841	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 "through-hole" "thru-hole" opening hole via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 15:31
S2	407	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 "through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (board substrate) near4 mount\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 15:32
S3	407	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 "through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (board substrate) near4 mount\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 15:33

S4	20	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 "through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit)and (board substrate) near4 mount\$3 and plat\$3 near5 wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 15:34
S5	68	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 "through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit)and (board substrate) near4 mount\$3 and plat\$3 near5 (line wire)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 15:39
S6	96	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 "through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit)and (board substrate) near4 mount\$3 and (electroplat\$5 plat\$3) near5 (line wire)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:01
S7	125	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit)and (board substrate) near4 mount\$3 and (electroplat\$5 plat\$3 power) near5 (line wire)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:45
S8	25	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit)and (board substrate) near4 mount\$3 and ((electroplat\$5 plat\$3) near5 (line wire)) with (power supply)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:21
S9	79	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit)and (board substrate) near4 mount\$3 and (line wire) with (power supply)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:23

S10	5	("205"/125.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit)and (board substrate) near4 mount\$3 and (line wire) with (power supply)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:23
S11	50	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit)and (board substrate) near4 mount\$3 and (electroplat\$5 plat\$3 power) near5 (line wire) and (au ni ag cr)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:46
S12	135	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3 power) near5 (line wire) and (au ni ag cr)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:47
S13	28	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (power) near5 (line wire) and (au ni ag cr)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:47
S14	39	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3 power) near5 (line wire) and (au ni ag cr) and lead\$3 near5 (line wire)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:51
S15	39	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3 power bus) near5 (line wire) and (au ni ag cr) and lead\$3 near5 (line wire)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 18:06

S16	438	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3 power bus) near5 (line wire) and (au ni ag cr) and lead\$3 near5 (line wire) not S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 17:04
S17	12	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3 power bus) near5 (line wire) and (au ni ag cr) and lead\$3 near5 (line wire) and cut near5 rout\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 17:06
S18	15	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3 power bus) near5 (line wire) and (au gold) and lead\$3 near5 (line wire) and cut near5 rout\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 17:17
S19	16	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3 power bus) near5 (line wire) and (au gold) and lead\$3 near5 (line wire) and cut\$4 near5 rout\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 18:05
S20	549	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3 power bus) near5 (line wire) and (au gold) and lead\$3 near5 (line wire) and (cut\$4 dic\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 18:06

S21	38	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3 power bus) near5 (line wire) and (au gold) and lead\$3 near5 (line wire) and (cut\$4 dic\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 18:25
S22	2	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (bus) near5 (line wire) and (au gold) and lead\$3 near5 (line wire) and (cut\$4 dic\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 18:14
S23	71	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (bus) near5 (line wire) and (au gold) and lead\$3 near5 (line wire) and (cut\$4 dic\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 18:14
S24	24	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3) near5 (line wire) and (au gold) and lead\$3 near5 (line wire) and (cut\$4 dic\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 11:14
S25	106	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3) near5 (line wire) and (au gold) and (cut\$4 dic\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 18:25
S26	106	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3) near5 (line wire) and (au gold) and (cut\$4 dic\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 11:21

S27	17	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("through-hole" "thru-hole" opening hole via) and ((board printed) near4 circuit) and (electroplat\$5 plat\$3) near5 (line wire) and (au gold) and (cut\$4 dicing) and matrix	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/22 10:51
S28	2	("6309528").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/19 12:15